

comprising the steps of:

Sub B 17

providing an open tank containing a liquid chemical;
providing a quartz gas distribution plate means submerged and supported
by bottom of said tank;
providing a pressure regulated gas supply means connected to said gas
distribution plate;
providing carrier means containing a plurality of substrates,
submerging and resting said carrier means on said gas distribution
plate so that a liquid chemical will all surfaces of said substrates that are
totally submersed and supported vertically;
said gas distribution plate generates and directs gas bubbles thereunder
and parallel to surfaces of substrates positioned thereabove, said gas
bubbles providing a chemical-mechanical scrubbing.

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12. (AMENDED) The method according to claim 11 further comprising
the steps of:

said provided quartz gas distribution plate means having a top surface
separated from a bottom surface, said bottom surface having a sinuous
groove with a flexible tubing urged into and guided by said sinuous
groove, each parallel leg of said sinuous groove having at least a pair of
holes formed through to said top surface, said holes are used as a drill jig
guide for drilling prescribed diameter holes in each leg of said flexible
tubing;

said flexible tubing having a first end connected to a gas supply means and
a second end that is capped;

13. (AMENDED) The method according to claim 11 further comprising

the steps of:

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said provided quartz gas distribution plate means having a plurality of elongated slot openings extending from the top surface to the bottom surface contiguously disposed between said parallel segments, said slot openings transversing length of said plate, said slot openings facilitate tank cleaning and maintenance.

14. (AMENDED) The method according to claim 11 wherein providing said process steps using a quartz gas distribution means eliminates photoresist residues in the hard to get places, such as wafers with top metal sidewalls that are coated with polymer, said method is cost effective compared with commercial megasonic or mechanical vibratory methods.

15 (AMENDED) A method for stripping photoresist from a plurality of semiconductor wafers having top metal lines with prominent sidewalls, comprising the steps of:

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providing an open tank containing a liquid stripper;

providing a quartz gas distribution plate means submerged and supported by bottom of said tank;

providing a pressure regulated gas supply means connected to said gas distribution plate:

providing cassette means containing a plurality of wafers, and submerging and resting said cassette means on said gas distribution plate so that a liquid chemical will contact all surfaces of said wafers that are submersed and supported vertically;

said gas distribution plate generates and directs gas bubbles thereunder and parallel to surfaces of wafers positioned thereabove said gas

bubbles providing a chemical-mechanical scrubbing.

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16. (AMENDED) The method according to claim 15 further comprising

the steps of:

said provided quartz gas distribution plate means having a top surface separated from a bottom surface, said bottom surface having a sinuous groove with a flexible tubing urged into and guided by said sinuous groove, each parallel leg of said sinuous groove having at least a pair of holes drilled through to said top surface, said holes are used as a drill jig guide for drilling prescribed diameter holes in each leg of said flexible tubing;

said flexible tubing having a first end connected to a gas supply means and a second end that is capped;

17. (AMENDED) The method according to claim 15 further comprising the steps of:

said provided quartz gas distribution plate means having a plurality of elongated slot openings extending from the top surface to the bottom surface contiguously disposed between said parallel segments, said slot openings transversing length of said plate, said slot openings facilitate tank cleaning and maintenance.